

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

DFN 5mm X 4mm Exp. Pad

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**TOTAL MASS (g) : 0.053858**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002879	1000000	53455.6484375		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.023117	975000	429223.40625		
		Iron (Fe)	7439-89-6	0.000569	24000	10564.8710938		
		Phosphorus (P)	7723-14-0	0.000007	300	129.972061157		
		Zinc (Zn)	7440-66-6	0.000017	700	315.64642334		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.023710</b>	<b>1000000</b>	<b>440233.875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.001124	1000000	20864.8378906		
		<b>External Plating Total:</b>				<b>0.001124</b>	<b>1000000</b>	<b>20864.8378906</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000522	1000000	9692.20214844		
<b>Internal Plating Total:</b>				<b>0.000522</b>	<b>1000000</b>	<b>9692.20214844</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001184	750000	21983.8457031		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000395	250000	7334.13720703		
<b>Die Attach Total:</b>				<b>0.001579</b>	<b>1000000</b>	<b>29317.9824219</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.003117	130000	57874.6992188		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.020623	860000	382916.25		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000240	10000	4456.18457031		
		<b>Encapsulation Total:</b>				<b>0.023980</b>	<b>1000000</b>	<b>445247.09375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000064	1000000	1188.31591797		
					<b>TOTAL MASS (g) :</b>	<b>0.053858</b>		